



Material Content Data Sheet



Sales Product Name	TLE7234EM			Issued		28. August 2013		
MA#	MA000982088							
Package	PG-SSOP-24-4			Weight*		150.84 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.306	2.85	2.85	28546	28546
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8917	
	non noble metal	copper	7440-50-8	54.617	36.21	37.15	362087	371561
wire	noble metal	gold	7440-57-5	0.478	0.32	0.32	3167	3167
encapsulation	organic material	carbon black	1333-86-4	0.171	0.11		1136	
	plastics	epoxy resin	-	7.881	5.22		52247	
	inorganic material	silicondioxide	60676-86-0	77.609	51.46	56.79	514517	567900
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19298	19298
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.301	0.20		1994	
	noble metal	silver	7440-22-4	0.902	0.60	0.80	5981	7975
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com